

Notice of References Cited	Application/Control No. 10/647,534	Applicant(s)/Patent Under Reexamination DIP ET AL.	
	Examiner Julio J. Maldonado	Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-2004/0121605 A1	06-2004	Maydan et al.	438/694
*	B	US-6,764,967 B1	07-2004	Pai et al.	438/787
*	C	US-6,613,677 B1	09-2003	Herbots et al.	438/694
*	D	US-6,589,877 B1	07-2003	Thakur, Randhir P.	438/703
*	E	US-6,573,197 B2	06-2003	Callegari et al.	438/791
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	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Park et al., A study of modified silicon surface after CHF/sub3//Clsub2/Fsub6/ reactive ion etching, ETRI-Journal (south Korea Vol.16, no.1, pages 45-47, April 1994.
	V	Wolf et al., Silicon Processing for the VLSI Era, Volume 1: Process Technology, 1986 by Lattice Press, pages 230-234, 568-574, 586-587 and 597-599.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.